

## **Hardware Test Engineer**

As a Hardware Test Engineer, you will be responsible for the operation of complex tools and processes to support microfabrication based packaging operations in an R&D laboratory environment. You will provide expertise in running chip bonding equipment and contribute a deep knowledge of related processes, materials, and methods. This position is held in a cleanroom environment with a full gowning protocol, collaborating with a cross-functional team of engineers. Daily responsibilities include supporting standard chip bonding processes, developing new packaging schemes and processes, oversight and maintenance of equipment, and execution of designed experiments.

### **Responsibilities**

- Expert-level operation of complex tools, including recipe development and oversight of maintenance on flip-chip bonding equipment.
- Maintain operation and throughput on chip bonding systems.
- Support lead engineers by performing DOE for new components, substrates, and/or materials.
- Work with engineering team members to design and execute new processes and methods.
- Verify process performance and product quality through the use of metrology equipment.

### **Minimum Qualifications**

- BS degree in related field or equivalent experience.
- Hands on experience with operating chip bonding tools and related processes in a cleanroom environment.
- Hands on experience with microfabrication equipment and processes.
- Hands on experience with handling Si wafers and other substrate form factors.
- Demonstrated ability to work independently in a fast-paced research environment.

### **Preferred Qualifications**

- Hands on experience independently using DOE methods to optimize process output.
- Expertise in test, inspection, and characterization methods.
- Proficiency with 3D CAD tools for designing custom fixtures for use in the bonding and assembly process.

### **Hiring manager**

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